

Welcome to O-leading

We are a professional PCB manufacturer with more than ten years of experience. Product range: single-sided, double-sided, multilayer PCB, flexible PCB and MCPCB. We can provide a rapid prototyping service: S / S in 24 hours, 4-8 units in 48-96 production hours.

MINIMUM COPPER PLATE HOLES .025 AVG, .020 MIN .. HOLES CAN NOT BE CONNECTED

Packaged with clear bubble colorless film, 25 pieces / bag, place the desiccant on the side, place the moisture indicator on top

CLICK HERE FOR MORE INFORMATION : [CERAMIC WAFER manufacturer china](#)

Product description

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PCB P / N	Q503701-A
Counting layers	2L
material	BASE ceramics
Board of directors	0.55 mm
copper thk	1/1 oz
Smallest hole size	1.6mm
Number of holes (pieces)	4
line w / s	/
Impedance check S / N (Tol%)	N
Surface finish	Electric silver
Silkscreen welding mask	green
Simple dimensions	Dim X (mm): 109; Dim Y (mm): 50
Panelisation	Dim X (mm): 109; Dim Y (mm): 50; UPS No: 1
Special: peelable mask	N
Routing / Punching	CNC

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www.o-leading.com

[Telecommunication PCB supplier china](#)

FAQ

1. How does O-Leading guarantee quality?

Our high quality standard is obtained with the following.

1. The process is strictly controlled in accordance with ISO 9001: 2008 standards.
2. Extensive use of software in the management of the production process
3. cutting-edge test tools and tools. For example. Flying Probe, X-ray inspection, AOI (Automated Optical Inspector) and ICT (circuit test).
4. Quality assurance team specified with fault case analysis process
5. Staff training and continuous training

2. How does O-Leading maintain the competitive price?

In the last decade, the prices of many raw materials (for example, copper, chemicals) had doubled, tripled or quadrupled; The Chinese currency RMB appreciated 31% against the US dollar; And our labor costs also increased significantly. However, O-Leading has kept our prices constant. It's all about our innovations to reduce costs, avoid waste and improve efficiency. Our prices are very competitive in the industry with the same level of quality.

We believe in a partnership of mutual benefit with our customers. Our partnership will be mutually beneficial if we can offer you an advantage in terms of cost and quality.

3. What types of cards can the O-Leading process make?

FR4 common, high TG and halogen-free boards, Rogers, Arlon, Telfon, aluminum / copper plates, PI,

etc.

4. What data are needed for PCB production?

It is better to provide data in the Gerber 274-X format. In addition, Cam350, CAD, Protel 99se, PADS, DXP and Eagle can also be processed.

5. What is the typical process flow for multi-layer PCB?

Cut material → inner dry film → internal engraving → internal AOI → Multi-bond → overlapping pressing layers → Drilling → PTH → Plating → external dry film → Plating → external engraving → AOI → external welding mask → COD component → Finishing surface → Routing → E / T → Visual inspection.

Our Team



Factory PCB



Automatic vacuum press machine



Drilling Machine



Pattern Plating Machine



Scrubbing Machine



Developing Machine



Routing Machine



High-speed flying probe machine



E-test Machine

Factory SMT



Certifications





No. SZXEC1900530401

Date: 30 Mar 2019

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O-LEADING SUPPLY CHAIN (HK) CO., LIMITED

1313, FLOOR 13, FORTUNE BUILDING, DANSHUI TOWN, HUIYANG DISTRICT, HUIZHOU, GUANGDONG, CHINA

The following sample(s) was/were submitted and identified on behalf of the clients as : OSP

SGS Job No. : RP19-005089 - SZ

Date of Sample Received : 22 Mar 2019

Testing Period : 22 Mar 2019 - 30 Mar 2019

Test Requested : Selected test(s) as requested by client.

Test Method : Please refer to next page(s).

Test Results : Please refer to next page(s).

Conclusion : Based on the performed tests on submitted sample(s), the results of Lead, Mercury, Cadmium, Hexavalent chromium, Polybrominated biphenyls (PBBs), Polybrominated diphenyl ethers (PBDEs) and Phthalates such as Bis(2-ethylhexyl) phthalate (DEHP), Butyl benzyl phthalate (BBP), Dibutyl phthalate (DBP), and Diisobutyl phthalate (DIBP) comply with the limits as set by RoHS Directive (EU) 2015/863 amending Annex II to Directive 2011/65/EU.

Signed for and on behalf of
SGS-CSTC Standards Technical Services Co., Ltd. Shenzhen Branch

Tina Fan
Approved Signatory

[illegible]

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No. SZXEC1900530401

Date: 30 Mar 2019

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Test Results :

Test Part Description:

Specimen No.	SGS Sample ID	Description
SN1	SZX19-005304.001	Green™PCB

Remarks :

(1) $1 \text{ mg/kg} = 1 \text{ ppm} = 0.0001\%$

(2) MDL = Method Detection Limit

(3) ND = Not Detected (< MDL)

(4) "-" = Not Regulated

RoHS Directive (EU) 2015/863 amending Annex II to Directive 2011/65/EU

Test Method : With reference to IEC 62321-4:2013+A1:2017, IEC62321-5:2013, IEC62321-7-2:2017, IEC 62321-6:2015 and IEC62321-8:2017, analyzed by ICP-OES, UV-Vis and GC-MS.

Test Item(s)	Limit	Unit	MDL	Q27
Cadmium (Cd)	100	mg/kg	2	ND
Lead (Pb)	1,000	mg/kg	2	8
Mercury (Hg)	1,000	mg/kg	2	ND
Hexavalent Chromium (Cr(VI))	1,000	mg/kg	8	ND
Sum of PBBs	1,000	mg/kg	-	ND
Monobromobiphenyl	-	mg/kg	5	ND
Dibromobiphenyl	-	mg/kg	5	ND
Tri bromobiphenyl	-	mg/kg	5	ND
Tetrabromobiphenyl	-	mg/kg	5	ND
Pentabromobiphenyl	-	mg/kg	5	ND
Hexabromobiphenyl	-	mg/kg	5	ND
Heptabromobiphenyl	-	mg/kg	5	ND
Octabromobiphenyl	-	mg/kg	5	ND
Nonabromobiphenyl	-	mg/kg	5	ND
Decabromobiphenyl	-	mg/kg	5	ND
Sum of PBDEs	1,000	mg/kg	-	ND
Monobromodiphenyl ether	-	mg/kg	5	ND
Dibromodiphenyl ether	-	mg/kg	5	ND
Tri bromodiphenyl ether	-	mg/kg	5	ND
Tetrabromodiphenyl ether	-	mg/kg	5	ND
Pentabromodiphenyl ether	-	mg/kg	5	ND



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ZPMV2.E490354 - WIRING, PRINTED - COMPONENT

Wiring, Printed - Component

See General Information for Wiring, Printed - Component

O-LEADING SUPPLY CHAIN (HK) CO LTD

E490354

ROOM 1205, 12/F
TAI SANG BANK BLDG
130-132 DES VOEUS ROAD
CENTRAL, HONG KONG

Type	Cond Width		Cond Thk mic(mil)	SS/ DS/ DSO	Max	Max					
	Min	Min			Area	Solder	Oper	Meets	C		
	Edge	Thk			Diam	Limits	Temp	Flame	UL796	T	
mm(in)	mm(in)			mm(in)	C	sec	C	Class	DSR	I	
Multilayer (mass laminate) printed wiring boards.											
O-LEADING-401	0.1 (0.004)	0.3 (0.012)	34 (1.34)	DS	12.7 (0.5)	260	10	130	V-0	-	-
O-LEADING-407	0.08 (0.003)	0.2 (0.008)	17 (0.67)	DS	9.7 (0.4)	260	10	130	V-0	All	-
Multilayer printed wiring boards.											
O-LEADING-408	0.125 (0.005)	0.125 (0.005)	12 (0.47) Int:136	DS	50.8 (2.0)	280	20	130	V-0	All	*
Single layer printed wiring boards.											
O-LEADING-002	0.38 (0.015)	1.14 (0.045)	34 (1.34)	SS	19.1 (0.8)	260	10	105	V-0	All	-
O-LEADING-003	0.38 (0.015)	1.14 (0.045)	34 (1.34)	SS	19.1 (0.8)	260	10	130	V-0	▲	-
O-LEADING-033	0.15 (0.006)	0.3 (0.012)	34 (1.34)	SS	25.4 (1.0)	260	10	120	V-0	All	-
O-LEADING-205	0.1 (0.004)	0.3 (0.012)	34 (1.34)	DS	69.6 (2.7)	260	10	130	V-0	All	-
O-LEADING-206	0.15 (0.006)	0.33 (0.013)	17 (0.67)	DS	69.6 (2.7)	260	10	130	V-0	All	-
O-LEADING-D01	0.14 (0.006)	0.15 (0.006)	33 (1.30)	DS	25.4 (1.0)	260	10	130	V-0	All	*
O-LEADING-S01	0.25 (0.010)	0.25 (0.010)	17 (0.67)	SS	25.4 (1.0)	260	4	130	V-0	All	*

WIRING, PRINTED - COMPONENT | UL Product iQ

O-LEADING-S02	0.2 (0.008)	0.2 (0.008)	17 (0.67)	SS	25.4 (1.0)	260	4	130	HB	▲	*
O-LEADING-S03	0.25 (0.010)	0.25 (0.010)	34 (1.34)	SS	25.4 (1.0)	260	4	130	V-0	All	*

* - CTI marking is optional and may be marked on the printed wiring board.

Marking: Company name or file number and type designation. May be followed by a suffix to denote factory identification or burning test classification.

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Packaging & Delivery

Shipping service



Quick Turn Lead Time		
Layer Count:	Lead Tim	Special Requirement
1L/2L	2-3days	24 Hours,48 Hours
4L	3-4days	48 Hours
6L	4-5days	72 Hours
8L	5-6days	NA
10L	6-7days	NA
12L	7-8days	NA
14L	8-9days	NA

Standard Lead Time		
Layer Count:	Sample Lead Time	Volume order lead time
2L	4 days	10 days
4L	5 days	11 days
6L	6 days	12 days
8L	8 days	14 days
10L	10 days	16 days
12L	12 days	18 days
14L	14 days	20 days
16-32L	18 days	24 days

Process Capability

PCB Production Capabilities

Layer Count: 1Layer-32Layer

Finished copper thickness□ 1/3oz-12oz

Min Line width/spacing internal□ 3.0mil/3.0mil

Min Line width/spacing external: 4.0mil/4.0mil

Max Aspect Ratio: 10:1

Board thickness□ 0.2mm-5.0mm

Max Panel size(inches): 635*1500mm

Minimum Drilled Hole Size: 4mil

Plated Hole Tolerance: +/-3mil

Blind/Buried Vias (All Types): YES

Via Fill(Conductive,Non-Conductive): YES

Base Material: FR-4,FR-4high Tg,Halogen free material,Rogers,Aluminium base,Polyimide,
Heavy Copper

Surface finishes: HASL,OSP,ENIG,HAL-LF,Immersion silver,Immersion Tin,Gold fingers,Carbon ink

SMT Production Capabilities

PCB Material: FR-4,CEM-1,CEM-3,Aluminum-based board

Max PCB size: 510x460mm

Min PCB size□50x50mm

PCB Thickness□0.5mm-4.5mm

Board thickness□0.5-4mm

Min Components size: 0201

Standard chip size component: 0603 and larger

Component max height□15mm

Min lead pitch: 0.3mm

Min BGA ball pitch:0.4mm

Placement precision: +/-0.03mm